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Details	
Product Status	Active
Number of LABs/CLBs	1172
Number of Logic Elements/Cells	18752
Total RAM Bits	239616
Number of I/O	142
Number of Gates	-
Voltage - Supply	1.15V ~ 1.25V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	240-BFQFP
Supplier Device Package	240-PQFP (32x32)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep2c20q240c8n

Section VII. PCB Layout Guidelines

Chapter 15. Package Information for Cyclone II Devices

Table 1–2. Cyclone II Package Options & Maximum User I/O Pins *Notes (1) (2)*

Device	144-Pin TQFP *(3)*	208-Pin PQFP *(4)*	240-Pin PQFP	256-Pin FineLine BGA	484-Pin FineLine BGA	484-Pin Ultra FineLine BGA	672-Pin FineLine BGA	896-Pin FineLine BGA
EP2C5 *(6) (8)*	89	142	—	158 *(5)*	—	—	—	—
EP2C8 *(6)*	85	138	—	182	—	—	—	—
EP2C8A *(6)*, *(7)*	—	—	—	182	—	—	—	—
EP2C15A *(6)*, *(7)*	—	—	—	152	315	—	—	—
EP2C20 *(6)*	—	—	142	152	315	—	—	—
EP2C20A *(6)*, *(7)*	—	—	—	152	315	—	—	—
EP2C35 *(6)*	—	—	—	—	322	322	475	—
EP2C50 *(6)*	—	—	—	—	294	294	450	—
EP2C70 *(6)*	—	—	—	—	—	—	422	622

Notes to Table 1–2:

(1) Cyclone II devices support vertical migration within the same package (for example, you can migrate between the EP2C20 device in the 484-pin FineLine BGA package and the EP2C35 and EP2C50 devices in the same package).

(2) The Quartus® II software I/O pin counts include four additional pins, `TDI`, `TDO`, `TMS`, and `TCK`, which are not available as general purpose I/O pins.

(3) TQFP: thin quad flat pack.

(4) PQFP: plastic quad flat pack.

(5) Vertical migration is supported between the EP2C5F256 and the EP2C8F256 devices. However, not all of the DQ and DQS groups are supported. Vertical migration between the EP2C5 and the EP2C15 in the F256 package is not supported.

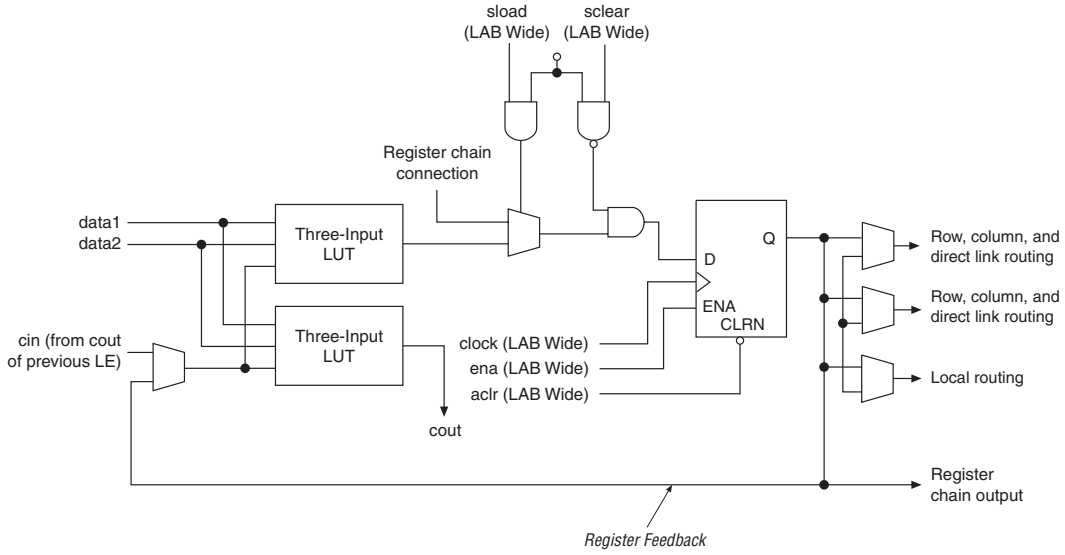
(6) The I/O pin counts for the EP2C5, EP2C8, and EP2C15A devices include 8 dedicated clock pins that can be used for data inputs. The I/O counts for the EP2C20, EP2C35, EP2C50, and EP2C70 devices include 16 dedicated clock pins that can be used for data inputs.

(7) EP2C8A, EP2C15A, and EP2C20A have a Fast On feature that has a faster POR time. The EP2C15A is only available with the Fast On option.

(8) The EP2C5 optionally support the Fast On feature, which is designated with an "A" in the device ordering code. The EP2C5A is only available in the automotive speed grade. Refer to the Cyclone II section in the *Automotive-Grade Device Handbook*.

Cyclone II devices support vertical migration within the same package (for example, you can migrate between the EP2C35, EPC50, and EP2C70 devices in the 672-pin FineLine BGA package). The exception to vertical migration support within the Cyclone II family is noted in Table 1–3.

Figure 2–4. LE in Arithmetic Mode



The Quartus II Compiler automatically creates carry chain logic during design processing, or you can create it manually during design entry. Parameterized functions such as LPM functions automatically take advantage of carry chains for the appropriate functions.

The Quartus II Compiler creates carry chains longer than 16 LEs by automatically linking LABs in the same column. For enhanced fitting, a long carry chain runs vertically, which allows fast horizontal connections to M4K memory blocks or embedded multipliers through direct link interconnects. For example, if a design has a long carry chain in a LAB column next to a column of M4K memory blocks, any LE output can feed an adjacent M4K memory block through the direct link interconnect. Whereas if the carry chains ran horizontally, any LAB not next to the column of M4K memory blocks would use other row or column interconnects to drive a M4K memory block. A carry chain continues as far as a full column.

In Cyclone II devices, all the I/O banks support SDR and DDR SDRAM memory up to 167 MHz/333 Mbps. All I/O banks support DQS signals with the DQ bus modes of ×8/×9, or ×16/×18. Table 2–14 shows the external memory interfaces supported in Cyclone II devices.

Table 2–14. External Memory Support in Cyclone II Devices *Note (1)*

Memory Standard	I/O Standard	Maximum Bus Width	Maximum Clock Rate Supported (MHz)	Maximum Data Rate Supported (Mbps)
SDR SDRAM	LVTTL *(2)*	72	167	167
DDR SDRAM	SSTL-2 class I *(2)*	72	167	333 *(1)*
	SSTL-2 class II *(2)*	72	133	267 *(1)*
DDR2 SDRAM	SSTL-18 class I *(2)*	72	167	333 *(1)*
	SSTL-18 class II *(3)*	72	125	250 *(1)*
QDRII SRAM *(4)*	1.8-V HSTL class I *(2)*	36	167	668 *(1)*
	1.8-V HSTL class II *(3)*	36	100	400 *(1)*

Notes to Table 2–14:

(1) The data rate is for designs using the Clock Delay Control circuitry.
(2) The I/O standards are supported on all the I/O banks of the Cyclone II device.
(3) The I/O standards are supported only on the I/O banks on the top and bottom of the Cyclone II device.
(4) For maximum performance, Altera recommends using the 1.8-V HSTL I/O standard because of higher I/O drive strength. QDRII SRAM devices also support the 1.5-V HSTL I/O standard.

Cyclone II devices use data (DQ), data strobe (DQS), and clock pins to interface with external memory. Figure 2–26 shows the DQ and DQS pins in the ×8/×9 mode.

Table 5–15. Cyclone II Performance (Part 4 of 4)

Applications		Resources Used			Performance (MHz)			
		LEs	M4K Memory Blocks	DSP Blocks	–6 Speed Grade	–7 Speed Grade *(6)*	–7 Speed Grade *(7)*	–8 Speed Grade
Larger Designs	8-bit, 1024 pt, Quad Output, 4 Parallel FFT Engines, Buffered Burst, 3 Mults/5 Adders FFT function	8053	60	36	200.0	195.0	149.23	163.02
	8-bit, 1024 pt, Quad Output, 4 Parallel FFT Engines, Buffered Burst, 4 Mults/2 Adders FFT function	7453	60	48	200.0	195.0	151.28	163.02

Notes to Table 5–15 :

(1) This application uses registered inputs and outputs.
(2) This application uses registered multiplier input and output stages within the DSP block.
(3) This application uses the same clock source for both A and B ports.
(4) This application uses independent clock sources for A and B ports.
(5) This application uses PLL clock outputs that are globally routed to connect and drive M4K clock ports. Use of non-PLL clock sources or local routing to drive M4K clock ports may result in lower performance numbers than shown here. Refer to the Quartus II timing report for actual performance numbers.
(6) These numbers are for commercial devices.
(7) These numbers are for automotive devices.

Internal Timing

Refer to Tables 5–16 through 5–19 for the internal timing parameters.

Table 5–16. LE_FF Internal Timing Microparameters (Part 1 of 2)

Parameter	–6 Speed Grade *(1)*		–7 Speed Grade *(2)*		–8 Speed Grade *(3)*		Unit
	Min	Max	Min	Max	Min	Max	
TSU	–36	—	–40	—	–40	—	ps
	—	—	–38	—	–40	—	ps
TH	266	—	306	—	306	—	ps
	—	—	286	—	306	—	ps
TCO	141	250	135	277	135	304	ps
	—	—	141	—	141	—	ps
TCLR	191	—	244	—	244	—	ps
	—	—	217	—	244	—	ps

I/O Delays

Refer to Tables 5–39 through 5–43 for I/O delays.

Table 5–39. I/O Delay Parameters

Symbol	Parameter
t_{DIP}	Delay from I/O datain to output pad
t_{OP}	Delay from I/O output register to output pad
t_{PCOUT}	Delay from input pad to I/O dataout to core
t_{PI}	Delay from input pad to I/O input register

Table 5–40. Cyclone II I/O Input Delay for Column Pins (Part 1 of 3)

I/O Standard	Parameter	Fast Corner		–6 Speed Grade	–7 Speed Grade (1)	–7 Speed Grade (2)	–8 Speed Grade	Unit
		Industrial/ Automotive	Commer -cial					
LVTTL	t_{PI}	581	609	1222	1228	1282	1282	ps
	t_{PCOUT}	367	385	760	783	854	854	ps
2.5V	t_{PI}	624	654	1192	1238	1283	1283	ps
	t_{PCOUT}	410	430	730	793	855	855	ps
1.8V	t_{PI}	725	760	1372	1428	1484	1484	ps
	t_{PCOUT}	511	536	910	983	1056	1056	ps
1.5V	t_{PI}	790	828	1439	1497	1556	1556	ps
	t_{PCOUT}	576	604	977	1052	1128	1128	ps
LVCMOS	t_{PI}	581	609	1222	1228	1282	1282	ps
	t_{PCOUT}	367	385	760	783	854	854	ps
SSTL_2_CLASS_I	t_{PI}	533	558	990	1015	1040	1040	ps
	t_{PCOUT}	319	334	528	570	612	612	ps
SSTL_2_CLASS_II	t_{PI}	533	558	990	1015	1040	1040	ps
	t_{PCOUT}	319	334	528	570	612	612	ps
SSTL_18_CLASS_I	t_{PI}	577	605	1027	1035	1045	1045	ps
	t_{PCOUT}	363	381	565	590	617	617	ps
SSTL_18_CLASS_II	t_{PI}	577	605	1027	1035	1045	1045	ps
	t_{PCOUT}	363	381	565	590	617	617	ps

Table 5–40. Cyclone II I/O Input Delay for Column Pins (Part 2 of 3)

I/O Standard	Parameter	Fast Corner		–6 Speed Grade	–7 Speed Grade (1)	–7 Speed Grade (2)	–8 Speed Grade	Unit
		Industrial/ Automotive	Commer -cial					
1.5V_HSTL_CLASS_I	t_{PI}	589	617	1145	1176	1208	1208	ps
	t_{PCOUT}	375	393	683	731	780	780	ps
1.5V_HSTL_CLASS_II	t_{PI}	589	617	1145	1176	1208	1208	ps
	t_{PCOUT}	375	393	683	731	780	780	ps
1.8V_HSTL_CLASS_I	t_{PI}	577	605	1027	1035	1045	1045	ps
	t_{PCOUT}	363	381	565	590	617	617	ps
1.8V_HSTL_CLASS_II	t_{PI}	577	605	1027	1035	1045	1045	ps
	t_{PCOUT}	363	381	565	590	617	617	ps
DIFFERENTIAL_SSTL_2_ CLASS_I	t_{PI}	533	558	990	1015	1040	1040	ps
	t_{PCOUT}	319	334	528	570	612	612	ps
DIFFERENTIAL_SSTL_2_ CLASS_II	t_{PI}	533	558	990	1015	1040	1040	ps
	t_{PCOUT}	319	334	528	570	612	612	ps
DIFFERENTIAL_SSTL_18_ CLASS_I	t_{PI}	577	605	1027	1035	1045	1045	ps
	t_{PCOUT}	363	381	565	590	617	617	ps
DIFFERENTIAL_SSTL_18_ CLASS_II	t_{PI}	577	605	1027	1035	1045	1045	ps
	t_{PCOUT}	363	381	565	590	617	617	ps
1.8V_DIFFERENTIAL_HSTL_ CLASS_I	t_{PI}	577	605	1027	1035	1045	1045	ps
	t_{PCOUT}	363	381	565	590	617	617	ps
1.8V_DIFFERENTIAL_HSTL_ CLASS_II	t_{PI}	577	605	1027	1035	1045	1045	ps
	t_{PCOUT}	363	381	565	590	617	617	ps
1.5V_DIFFERENTIAL_HSTL_ CLASS_I	t_{PI}	589	617	1145	1176	1208	1208	ps
	t_{PCOUT}	375	393	683	731	780	780	ps
1.5V_DIFFERENTIAL_HSTL_ CLASS_II	t_{PI}	589	617	1145	1176	1208	1208	ps
	t_{PCOUT}	375	393	683	731	780	780	ps
LVDS	t_{PI}	623	653	1072	1075	1078	1078	ps
	t_{PCOUT}	409	429	610	630	650	650	ps
1.2V_HSTL	t_{PI}	570	597	1263	1324	1385	1385	ps
	t_{PCOUT}	356	373	801	879	957	957	ps

Table 5–42. Cyclone II I/O Output Delay for Column Pins (Part 5 of 6)

I/O Standard	Drive Strength	Parameter	Fast Corner		–6 Speed Grade	–7 Speed Grade (2)	–7 Speed Grade (3)	–8 Speed Grade	Unit
			Industrial/ Automotive	Commer -cial					
DIFFERENTIAL_ SSTL_18_CLASS_I	6 mA	t_{OP}	1472	1544	3140	3345	3542	3549	ps
		t_{DIP}	1604	1683	3310	3539	3768	3768	ps
	8 mA	t_{OP}	1469	1541	3086	3287	3482	3489	ps
		t_{DIP}	1601	1680	3256	3481	3708	3708	ps
	10 mA	t_{OP}	1466	1538	2980	3171	3354	3361	ps
		t_{DIP}	1598	1677	3150	3365	3580	3580	ps
	12 mA (1)	t_{OP}	1466	1538	2980	3171	3354	3361	ps
		t_{DIP}	1598	1677	3150	3365	3580	3580	ps
DIFFERENTIAL_ SSTL_18_CLASS_II	16 mA	t_{OP}	1454	1525	2905	3088	3263	3270	ps
		t_{DIP}	1586	1664	3075	3282	3489	3489	ps
	18 mA (1)	t_{OP}	1453	1524	2900	3082	3257	3264	ps
		t_{DIP}	1585	1663	3070	3276	3483	3483	ps
1.8V_DIFFERENTIAL _HSTL_CLASS_I	8 mA	t_{OP}	1460	1531	3222	3424	3618	3625	ps
		t_{DIP}	1592	1670	3392	3618	3844	3844	ps
	10 mA	t_{OP}	1462	1534	3090	3279	3462	3469	ps
		t_{DIP}	1594	1673	3260	3473	3688	3688	ps
	12 mA (1)	t_{OP}	1462	1534	3090	3279	3462	3469	ps
		t_{DIP}	1594	1673	3260	3473	3688	3688	ps
1.8V_DIFFERENTIAL _HSTL_CLASS_II	16 mA	t_{OP}	1449	1520	2936	3107	3271	3278	ps
		t_{DIP}	1581	1659	3106	3301	3497	3497	ps
	18 mA	t_{OP}	1450	1521	2924	3101	3272	3279	ps
		t_{DIP}	1582	1660	3094	3295	3498	3498	ps
	20 mA (1)	t_{OP}	1452	1523	2926	3096	3259	3266	ps
		t_{DIP}	1584	1662	3096	3290	3485	3485	ps
1.5V_DIFFERENTIAL _HSTL_CLASS_I	8 mA	t_{OP}	1779	1866	4292	4637	4974	4981	ps
		t_{DIP}	1911	2005	4462	4831	5200	5200	ps
	10 mA	t_{OP}	1784	1872	4031	4355	4673	4680	ps
		t_{DIP}	1916	2011	4201	4549	4899	4899	ps
	12 mA (1)	t_{OP}	1784	1872	4031	4355	4673	4680	ps
		t_{DIP}	1916	2011	4201	4549	4899	4899	ps

= 1000 / (1000/toggle rate at default load + derating factor * load value in pF/1000)

For example, the output toggle rate at 0 pF (default) load for SSTL-18 Class II 18mA I/O standard is 270 MHz on a –6 device column I/O pin. The derating factor is 29 ps/pF. For a 10pF load, the toggle rate is calculated as:

1000 / (1000/270 + 29 × 10/1000) = 250 (MHz)

Tables 5–44 through 5–46 show the I/O toggle rates for Cyclone II devices.

Table 5–44. Maximum Input Clock Toggle Rate on Cyclone II Devices (Part 1 of 2)

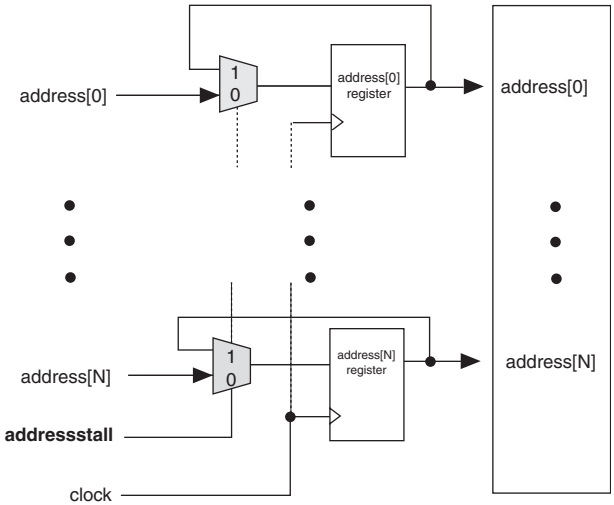
I/O Standard	Maximum Input Clock Toggle Rate on Cyclone II Devices (MHz)								
	Column I/O Pins			Row I/O Pins			Dedicated Clock Inputs		
	–6 Speed Grade	–7 Speed Grade	–8 Speed Grade	–6 Speed Grade	–7 Speed Grade	–8 Speed Grade	–6 Speed Grade	–7 Speed Grade	–8 Speed Grade
LVTTL	450	405	360	450	405	360	420	380	340
2.5V	450	405	360	450	405	360	450	405	360
1.8V	450	405	360	450	405	360	450	405	360
1.5V	300	270	240	300	270	240	300	270	240
LVCMOS	450	405	360	450	405	360	420	380	340
SSTL_2_CLASS_I	500	500	500	500	500	500	500	500	500
SSTL_2_CLASS_II	500	500	500	500	500	500	500	500	500
SSTL_18_CLASS_I	500	500	500	500	500	500	500	500	500
SSTL_18_CLASS_II	500	500	500	500	500	500	500	500	500
1.5V_HSTL_CLASS_I	500	500	500	500	500	500	500	500	500
1.5V_HSTL_CLASS_II	500	500	500	500	500	500	500	500	500
1.8V_HSTL_CLASS_I	500	500	500	500	500	500	500	500	500
1.8V_HSTL_CLASS_II	500	500	500	500	500	500	500	500	500
PCI	—	—	—	350	315	280	350	315	280
PCI-X	—	—	—	350	315	280	350	315	280
DIFFERENTIAL_SSTL_2_CLASS_I	500	500	500	500	500	500	500	500	500
DIFFERENTIAL_SSTL_2_CLASS_II	500	500	500	500	500	500	500	500	500

Table 5–45. Maximum Output Clock Toggle Rate on Cyclone II Devices (Part 3 of 4)

I/O Standard	Drive Strength	Maximum Output Clock Toggle Rate on Cyclone II Devices (MHz)								
		Column I/O Pins *(1)*			Row I/O Pins *(1)*			Dedicated Clock Outputs		
		–6 Speed Grade	–7 Speed Grade	–8 Speed Grade	–6 Speed Grade	–7 Speed Grade	–8 Speed Grade	–6 Speed Grade	–7 Speed Grade	–8 Speed Grade
SSTL_18_ CLASS_II	16 mA	260	220	180	—	—	—	—	—	—
	18 mA	270	220	180	—	—	—	—	—	—
1.8V_HSTL_ CLASS_I	8 mA	260	220	180	260	220	180	260	220	180
	10 mA	300	250	210	300	250	210	300	250	210
	12 mA	320	270	220	320	270	220	320	270	220
1.8V_HSTL_ CLASS_II	16 mA	230	190	160	—	—	—	—	—	—
	18 mA	240	200	160	—	—	—	—	—	—
	20 mA	250	210	170	—	—	—	—	—	—
1.5V_HSTL_ CLASS_I	8 mA	210	170	140	210	170	140	210	170	140
	10 mA	220	180	150	—	—	—	—	—	—
	12 mA	230	190	160	—	—	—	—	—	—
1.5V_HSTL_ CLASS_II	16 mA	210	170	140	—	—	—	—	—	—
DIFFERENTIAL_ SSTL_2_CLASS_I	8 mA	400	340	280	400	340	280	400	340	280
	12 mA	400	340	280	400	340	280	400	340	280
DIFFERENTIAL_ SSTL_2_CLASS_II	16 mA	350	290	240	350	290	240	350	290	240
	20 mA	400	340	280	—	—	—	—	—	—
	24 mA	400	340	280	—	—	—	—	—	—
DIFFERENTIAL_ SSTL_18_CLASS_I	6 mA	260	220	180	260	220	180	260	220	180
	8 mA	260	220	180	260	220	180	260	220	180
	10 mA	270	220	180	270	220	180	270	220	180
	12 mA	280	230	190	—	—	—	—	—	—
DIFFERENTIAL_SSTL _18_CLASS_II	16 mA	260	220	180	—	—	—	—	—	—
	18 mA	270	220	180	—	—	—	—	—	—
1.8V_ DIFFERENTIAL_HSTL _CLASS_I	8 mA	260	220	180	260	220	180	260	220	180
	10 mA	300	250	210	300	250	210	300	250	210
	12 mA	320	270	220	320	270	220	320	270	220
1.8V_ DIFFERENTIAL_HSTL _CLASS_II	16 mA	230	190	160	—	—	—	—	—	—
	18 mA	240	200	160	—	—	—	—	—	—
	20 mA	250	210	170	—	—	—	—	—	—

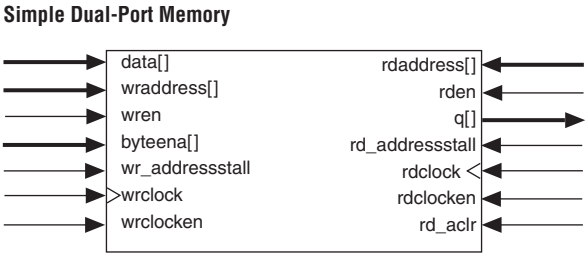
Figure 8–3 shows an address clock enable block diagram. The address register output is fed back to its input via a multiplexer. The multiplexer output is selected by the address clock enable (`addressstall`) signal. Address latching is enabled when the `addressstall` signal goes high (active high). The output of the address register is then continuously fed into the input of the register until the `addressstall` signal goes low.

Figure 8–3. Cyclone II Address Clock Enable Block Diagram



The address clock enable is typically used for cache memory applications to improve efficiency during a cache-miss. The default value for the address clock enable signals is low (disabled). Figures 8–4 and 8–5 show the address clock enable waveforms during the read and write cycles, respectively.

Figure 8–8. Cyclone II Simple Dual-Port Mode *Note (1)*



Note to Figure 8–8:
(1) Simple dual-port RAM supports input and output clock mode in addition to the read and write clock mode shown.

Cyclone II memory blocks support mixed-width configurations, allowing different read and write port widths. Tables 8–5 and 8–6 show the mixed-width configurations.

Table 8–5. Cyclone II Memory Block Mixed-Width Configurations (Simple Dual-Port Mode)

Read Port	Write Port								
	4K × 1	2K × 2	1K × 4	512 × 8	256 × 16	128 × 32	512 × 9	256 × 18	128 × 36
4K × 1	✓	✓	✓	✓	✓	✓			
2K × 2	✓	✓	✓	✓	✓	✓			
1K × 4	✓	✓	✓	✓	✓	✓			
512 × 8	✓	✓	✓	✓	✓	✓			
256 × 16	✓	✓	✓	✓	✓	✓			
128 × 32	✓	✓	✓	✓	✓	✓			
512 × 9							✓	✓	✓
256 × 18							✓	✓	✓
128 × 36							✓	✓	✓

In simple dual-port mode, the memory blocks have one write enable and one read enable signal. They do not support a clear port on the write enable and read enable registers. When the read enable is deactivated, the current data is retained at the output ports. If the read enable is activated during a write operation with the same address location selected, the simple dual-port RAM output is the old data stored at the memory

applications require local data storage, traditionally implemented with standard flip-flops that quickly exhaust many logic cells for large shift registers. A more efficient alternative is to use embedded memory as a shift register block, which saves logic cell and routing resources.

The size of a ($w \times m \times n$) shift register is determined by the input data width (w), the length of the taps (m), and the number of taps (n), and must be less than or equal to the maximum number of memory bits, which is 4,608 bits. In addition, the size of ($w \times n$) must be less than or equal to the maximum width of the block, which is 36 bits. If a larger shift register is required, the memory blocks can be cascaded.

Data is written into each address location at the falling edge of the clock and read from the address at the rising edge of the clock. The shift register mode logic automatically controls the positive and negative edge clocking to shift the data in one clock cycle. Figure 8–12 shows the Cyclone II memory block in the shift register mode.

Figure 8–12. Cyclone II Shift Register Mode Configuration

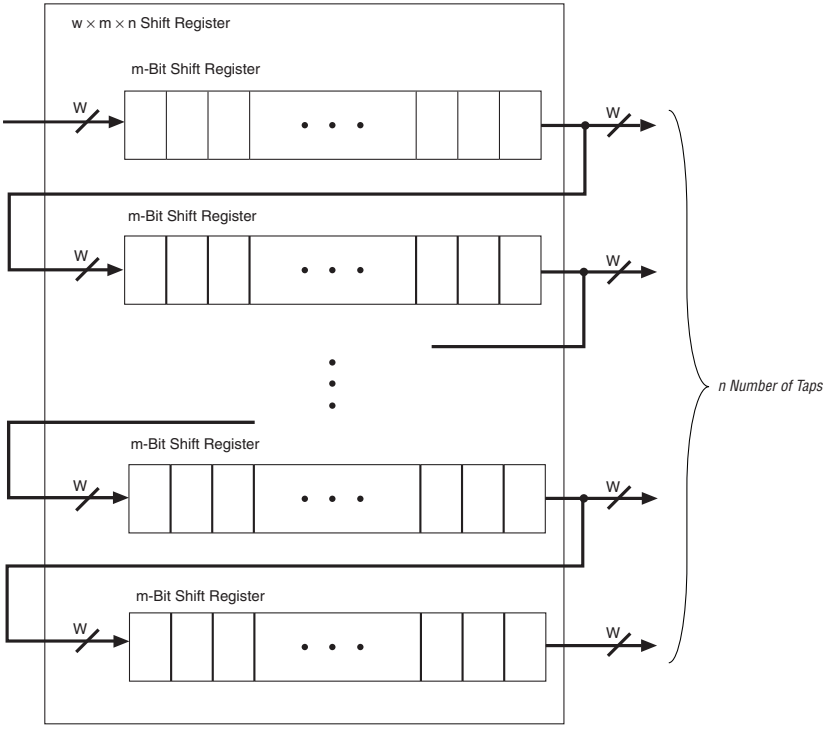
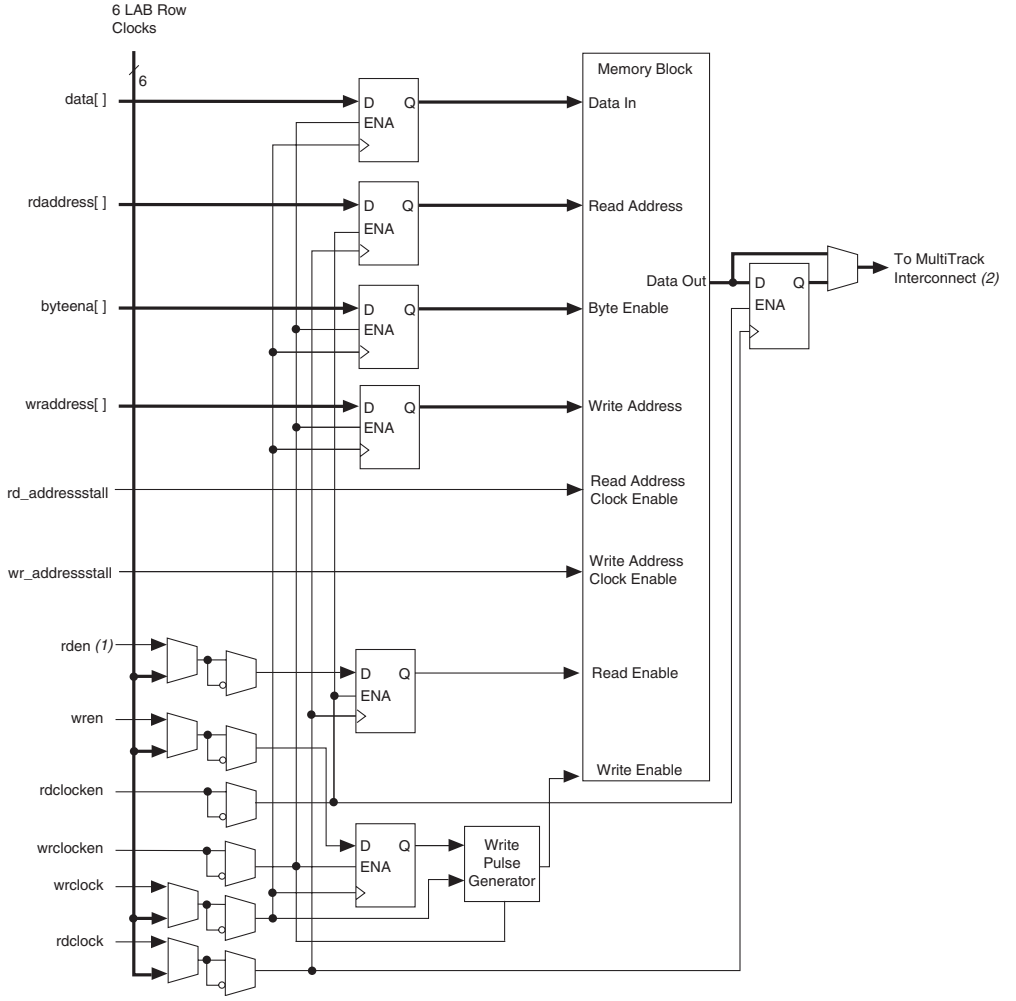


Figure 8–17. Cyclone II Read/Write Clock Mode *Notes (1), (2)*

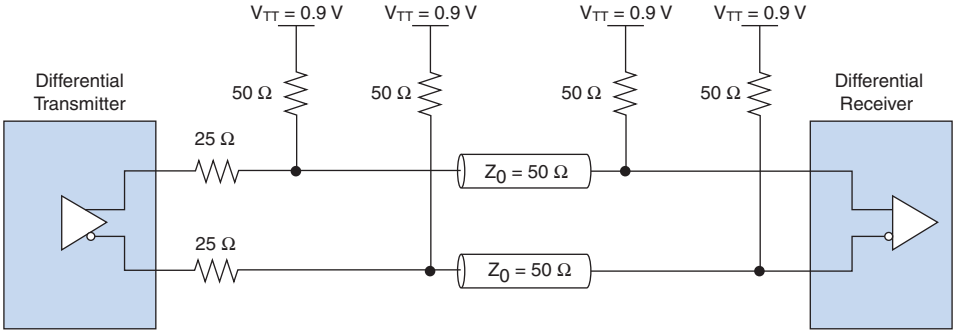


Notes to Figure 8–17:

(1) Violating the setup or hold time on the memory block address registers could corrupt memory contents. This applies to both read and write operations.

(2) For more information about the MultiTract interconnect, refer to *Cyclone II Device Family Data Sheet* in volume 1 of the *Cyclone II Device Handbook*.

Figure 10–10. Differential SSTL-18 Class II Termination



1.8-V Pseudo-Differential HSTL Class I and II

The 1.8-V differential HSTL specification is the same as the 1.8-V single-ended HSTL specification. It is used for applications designed to operate in the 0.0 to 1.8-V HSTL logic switching range such as QDR memory clock interfaces. Cyclone II devices support both input and output levels. Refer to Figures 10–11 and 10–12 for details on 1.8-V differential HSTL termination.

Cyclone II devices do not support true 1.8-V differential HSTL standards. Cyclone II devices support pseudo-differential HSTL outputs for `PLL_OUT` pins and pseudo-differential HSTL inputs for clock pins. Pseudo-differential inputs require an input reference voltage as opposed to the true differential inputs. Refer to Table 10–1 on page 10–2 for information about pseudo-differential HSTL.

Figure 10–11. 1.8-V Differential HSTL Class I Termination

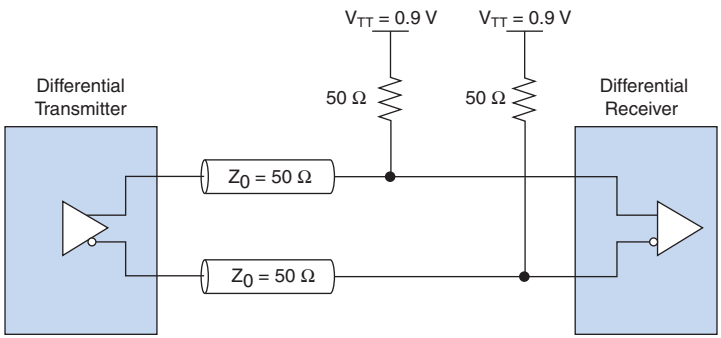
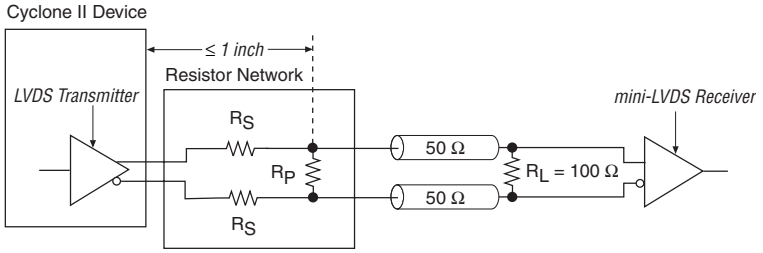


Figure 11–10. mini-LVDS Resistor Network



Note to Figure 11–10:
(1) R_S = 120 Ω and R_P = 170 Ω

mini-LVDS Software Support

When designing for the mini-LVDS I/O standard, assign the mini-LVDS I/O standard to the I/O pins intended for mini-LVDS in the Quartus II software. Contact Altera Applications for reference designs.

LVPECL Support in Cyclone II

The LVPECL I/O standard is a differential interface standard requiring a 3.3-V V_{CCIO} and is used in applications involving video graphics, telecommunications, data communications, and clock distribution. The high-speed, low-voltage swing LVPECL I/O standard uses a positive power supply and is similar to LVDS. However, LVPECL has a larger differential output voltage swing than LVDS. Cyclone II devices support the LVPECL input standard at the clock input pins only. Table 11–4 shows the LVPECL electrical characteristics for Cyclone II devices. Figure 11–11 shows the LVPECL I/O interface.

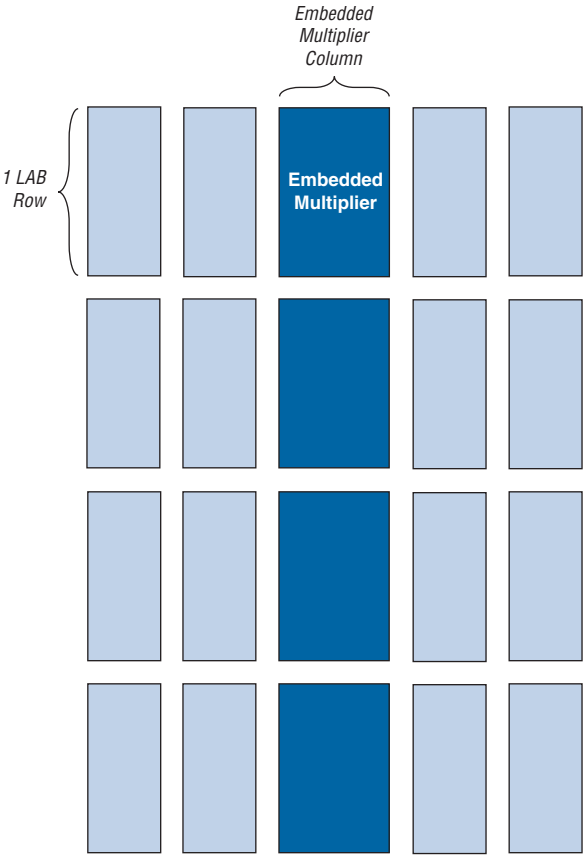
Table 11–4. LVPECL Electrical Characteristics for Cyclone II Devices

Symbol	Parameters	Condition	Min	Typ	Max	Units
V_{CCIO}	Output supply voltage		3.135	3.3	3.465	V
V_{IH}	Input high voltage		2,100		2,880	mV
V_{IL}	Input low voltage		0		2,200	mV
V_{ID}	Differential input voltage	Peak to peak	100	600	950	mV

Embedded Multiplier Block Overview

Each Cyclone II device has one to three columns of embedded multipliers that implement multiplication functions. Figure 12–1 shows one of the embedded multiplier columns with the surrounding LABs. Each embedded multiplier can be configured to support one 18 × 18 multiplier or two 9 × 9 multipliers.

Figure 12–1. Embedded Multipliers Arranged in Columns with Adjacent LABs



Configuration File Format

Table 13–3 shows the approximate uncompressed configuration file sizes for Cyclone II devices. To calculate the amount of storage space required for multiple device configurations, add the file size of each device together.

Table 13–3. Cyclone II Raw Binary File (.rbf) Sizes *Note (1)*

Device	Data Size (Bits)	Data Size (Bytes)
EP2C5	1,265,792	152,998
EP2C8	1,983,536	247,974
EP2C15	3,892,496	486,562
EP2C20	3,892,496	486,562
EP2C35	6,858,656	857,332
EP2C50	9,963,392	1,245,424
EP2C70	14,319,216	1,789,902

Note to Table 13–3:
(1) These values are preliminary.

Use the data in Table 13–3 only to estimate the file size before design compilation. Different configuration file formats, such as a Hexadecimal (**.hex**) or Tabular Text File (**.ttf**) format, have different file sizes. However, for any specific version of the Quartus® II software, any design targeted for the same device has the same uncompressed configuration file size. If compression is used, the file size can vary after each compilation since the compression ratio is dependent on the design.

Configuration Data Compression

Cyclone II devices support configuration data decompression, which saves configuration memory space and time. This feature allows you to store compressed configuration data in configuration devices or other memory and transmit this compressed bitstream to Cyclone II devices. During configuration, the Cyclone II device decompresses the bitstream in real time and programs its SRAM cells.

Preliminary data indicates that compression reduces configuration bitstream size by 35 to 55%.

Cyclone II devices support decompression in the AS and PS configuration schemes. Decompression is not supported in JTAG-based configuration.

Figure 15–1 shows a 144-pin TQFP package outline.

Figure 15–1. 144-Pin TQFP Package Outline

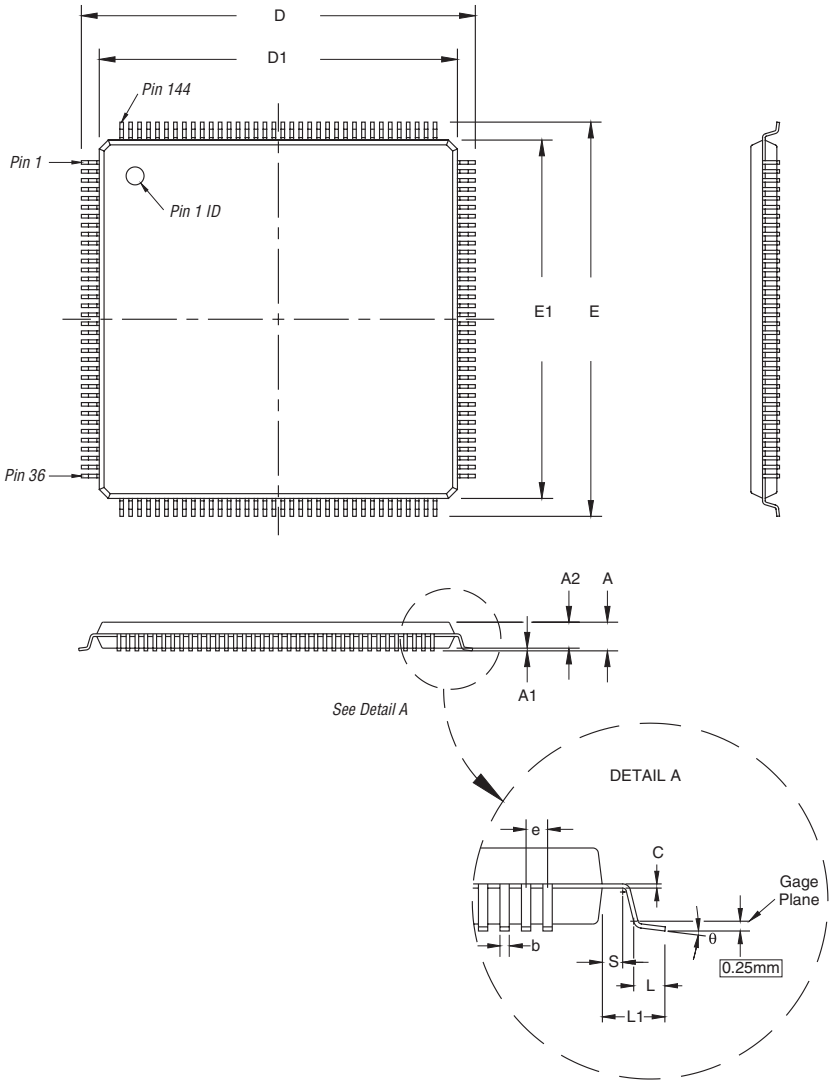


Table 15–8. 208-Pin PQFP Package Outline Dimensions (Part 2 of 2)			
Symbol	Millimeter		
	Min.	Nom.	Max.
e	0.50 BSC		
q	0°	3.5°	8°

Figure 15–2 shows a 208-pin PQFP package outline.

Figure 15–2. 208-pin PQFP Package Outline